

## DualCool™ N-Channel NexFET™ Power MOSFETs

 Check for Samples: [CSD16322Q5C](#)

### FEATURES

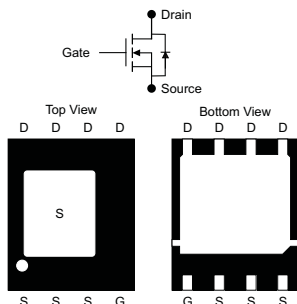
- DualCool™ Package SON 5x6mm
- Optimized for Two Sided Cooling
- Optimized for 5V Gate Drive
- Ultralow  $Q_g$  and  $Q_{gd}$
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant and Halogen Free

### APPLICATIONS

- Point-of-Load Synchronous Buck in Networking, Telecom and Computing Systems
- Optimized for Synchronous or Control FET Applications

### DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications and optimized for 5V gate drive applications.



### PRODUCT SUMMARY

$V_{DS}$	Drain to Source Voltage	25	V
$Q_g$	Gate Charge Total (4.5V)	6.8	nC
$Q_{gd}$	Gate Charge Gate to Drain	1.3	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V$	5.4 mΩ
		$V_{GS} = 4.5V$	4.6 mΩ
		$V_{GS} = 8V$	3.9 mΩ
$V_{GS(th)}$	Threshold Voltage	1.1	V

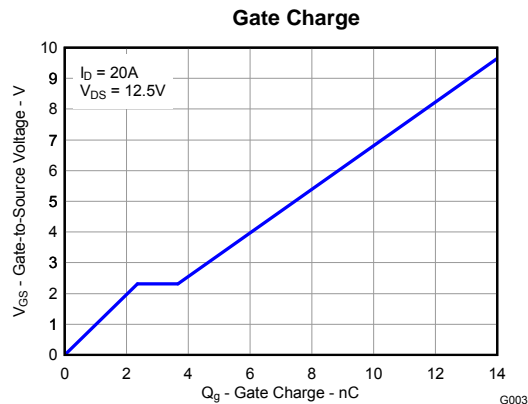
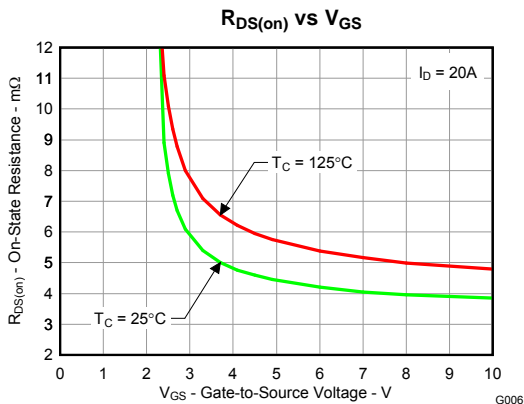
### ORDERING INFORMATION

Device	Package	Media	Qty	Ship
CSD16322Q5C	SON 5x6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

### ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
$V_{DS}$	Drain to Source Voltage	25	V
$V_{GS}$	Gate to Source Voltage	+10 / -8	V
$I_D$	Continuous Drain Current, $T_C = 25^\circ\text{C}$	97	A
	Continuous Drain Current <sup>(1)</sup>	21	A
$I_{DM}$	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ <sup>(2)</sup>	136	A
$P_D$	Power Dissipation <sup>(1)</sup>	3.1	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Avalanche Energy, single pulse $I_D = 50A, L = 0.1\text{mH}, R_G = 25\Omega$	125	mJ

- (1)  $R_{\theta JA} = 39^\circ\text{C/W}$  on 1-inch<sup>2</sup> Cu, (2-oz.) on a 0.06" thick FR4 PCB.  
 (2) Pulse duration  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$



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DualCool, NexFET are trademarks of Texas Instruments.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain to Source Voltage	$V_{GS} = 0V, I_{DS} = 250\mu A$	25			V
$I_{DSS}$	Drain to Source Leakage	$V_{GS} = 0V, V_{DS} = 20V$			1	$\mu A$
$I_{GSS}$	Gate to Source Leakage	$V_{DS} = 0V, V_{GS} = +10/-8V$			100	nA
$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.9	1.1	1.4	V
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V, I_{DS} = 20A$		5.4	7.2	m $\Omega$
		$V_{GS} = 4.5V, I_{DS} = 20A$		4.6	5.8	m $\Omega$
		$V_{GS} = 8V, I_{DS} = 20A$		3.9	5	m $\Omega$
$g_{fs}$	Transconductance	$V_{DS} = 15V, I_{DS} = 20A$		106		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = 12.5V,$ $f = 1MHz$	1050	1365		pF
$C_{oss}$	Output Capacitance		740	950		pF
$C_{rss}$	Reverse Transfer Capacitance		55	70		pF
$R_G$	Series Gate Resistance		1.1	2.2		$\Omega$
$Q_g$	Gate Charge Total (4.5V)	$V_{DS} = 12.5V,$ $I_{DS} = 20A$	6.8	9.7		nC
$Q_{gd}$	Gate Charge – Gate to Drain		1.3			nC
$Q_{gs}$	Gate Charge – Gate to Source		2.4			nC
$Q_{g(th)}$	Gate Charge at $V_{th}$		1.3			nC
$Q_{oss}$	Output Charge	$V_{DS} = 13V, V_{GS} = 0V$	17			nC
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = 12.5V, V_{GS} = 4.5V,$ $I_{DS} = 20A, R_G = 2\Omega$	6.1			ns
$t_r$	Rise Time		10.7			ns
$t_{d(off)}$	Turn Off Delay Time		12.3			ns
$t_f$	Fall Time		3.7			ns
<b>Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{DS} = 20A, V_{GS} = 0V$	0.8	1		V
$Q_{rr}$	Reverse Recovery Charge	$V_{DD} = 13V, I_F = 20A, di/dt = 300A/\mu s$	19			nC
$t_{rr}$	Reverse Recovery Time		21			ns

## THERMAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Thermal Resistance Junction to Case (Top Source) <sup>(1)</sup>			3.5	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case (Bottom drain) <sup>(1)</sup>			2.4	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient <sup>(1)(2)</sup>			50	$^\circ\text{C/W}$

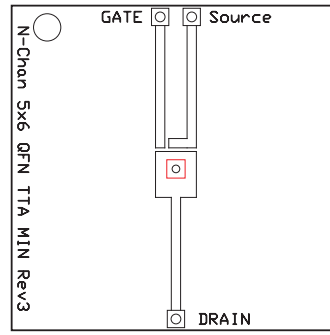
(1)  $R_{\theta JC}$  is determined with the device mounted on a 1-inch<sup>2</sup> 2-oz. Cu pad on a 1.5 × 1.5-inch 0.06-inch thick FR4 board.  $R_{\theta JC}$  is specified by design, whereas  $R_{\theta CA}$  is determined by the user's board design.

(2) Device mounted on FR4 material with 1-inch<sup>2</sup> of 2-oz. Cu.



M0137-01

Max  $R_{\theta JA} = 50^{\circ}\text{C/W}$   
when mounted on  
1 inch<sup>2</sup> of 2-oz. Cu.

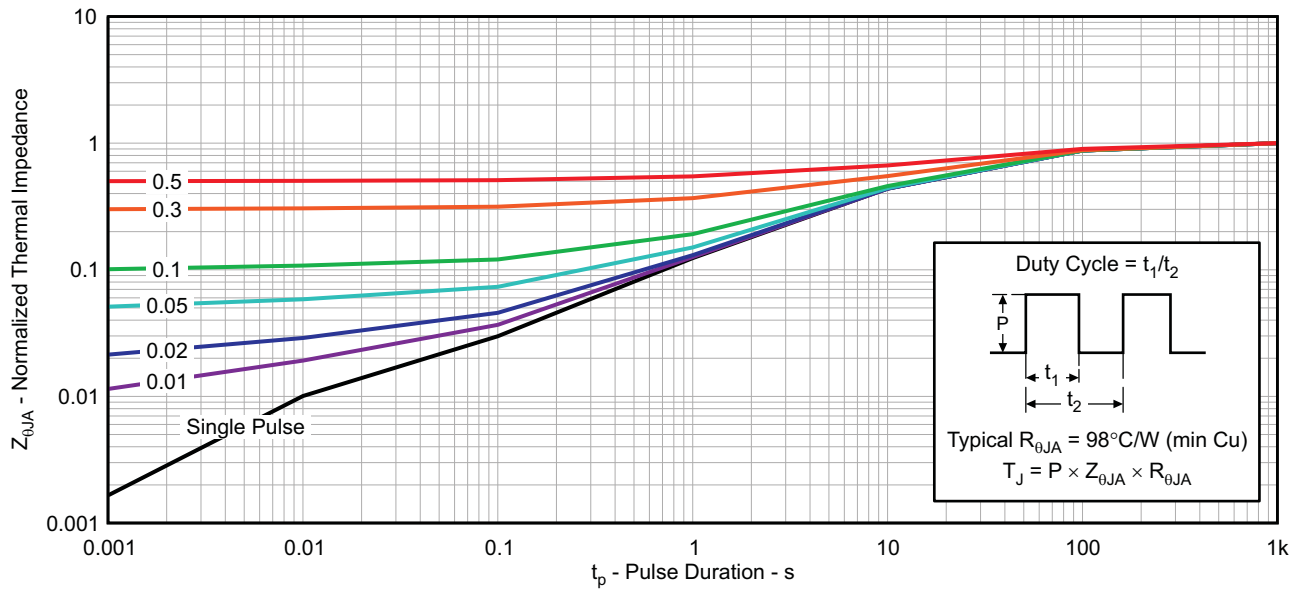


M0137-02

Max  $R_{\theta JA} = 123^{\circ}\text{C/W}$   
when mounted on  
minimum pad area of  
2-oz. Cu.

### TYPICAL MOSFET CHARACTERISTICS

( $T_A = 25^{\circ}\text{C}$  unless otherwise stated)

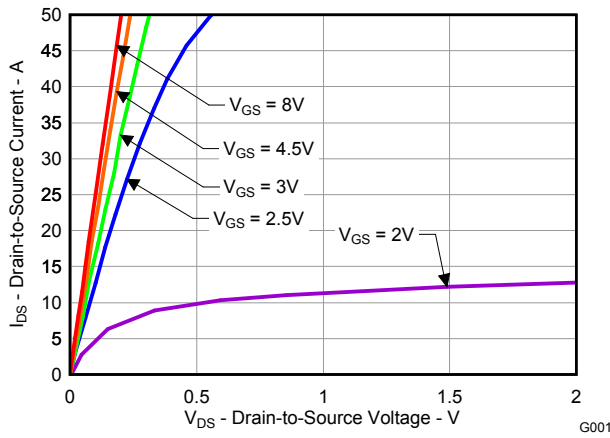


G012

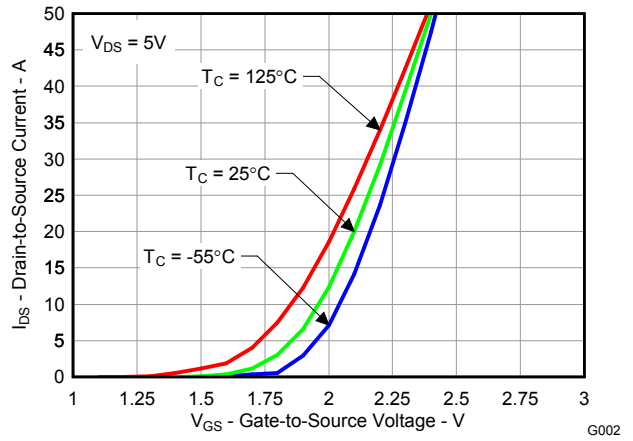
Figure 1. Transient Thermal Impedance

**TYPICAL MOSFET CHARACTERISTICS (continued)**

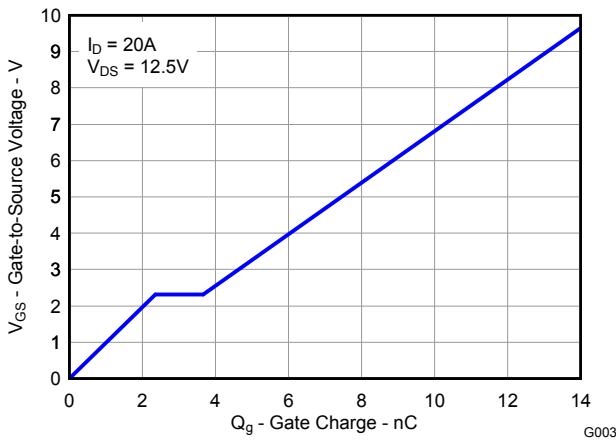
( $T_A = 25^\circ\text{C}$  unless otherwise stated)



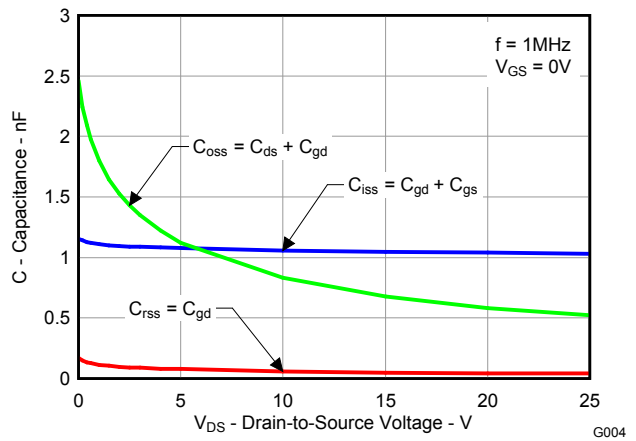
**Figure 2. Saturation Characteristics**



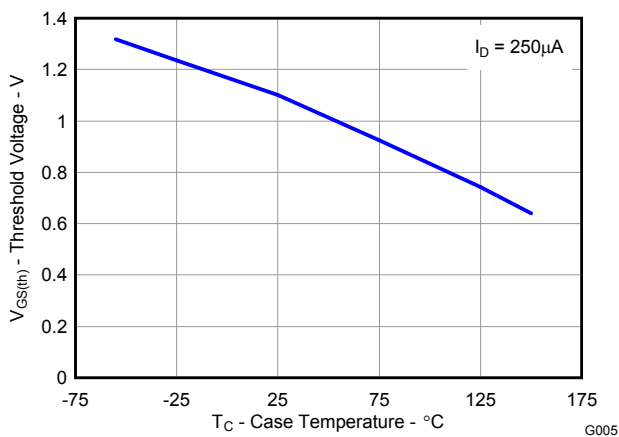
**Figure 3. Transfer Characteristics**



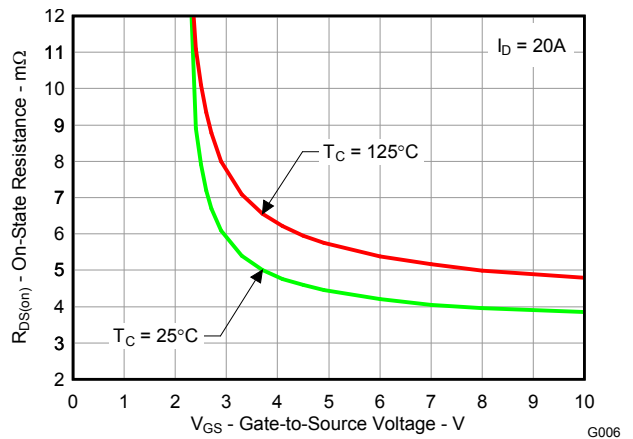
**Figure 4. Gate Charge**



**Figure 5. Capacitance**



**Figure 6. Threshold Voltage vs. Temperature**



**Figure 7. On Resistance vs. Gate Voltage**

TYPICAL MOSFET CHARACTERISTICS (continued)

( $T_A = 25^\circ\text{C}$  unless otherwise stated)

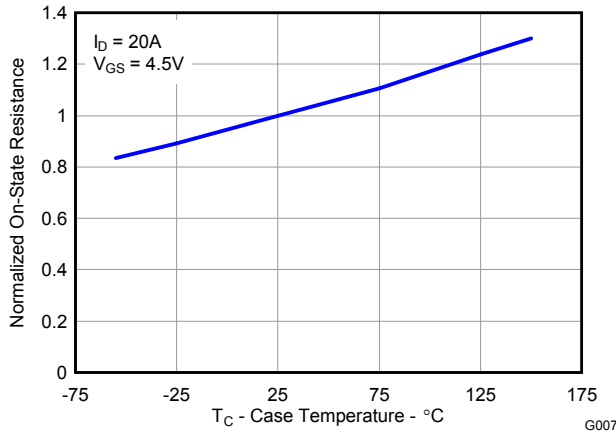


Figure 8. On Resistance vs. Temperature

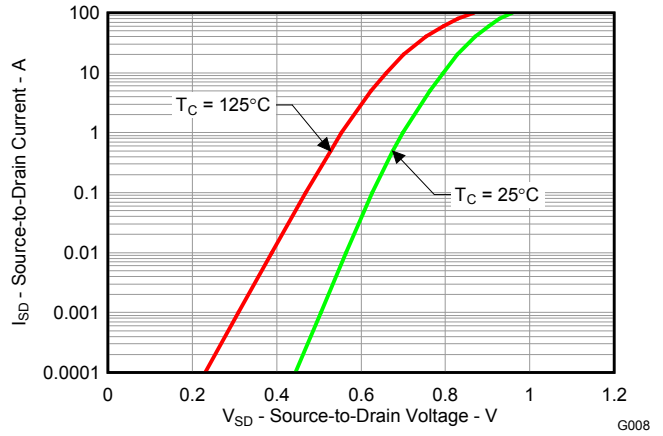


Figure 9. Typical Diode Forward Voltage

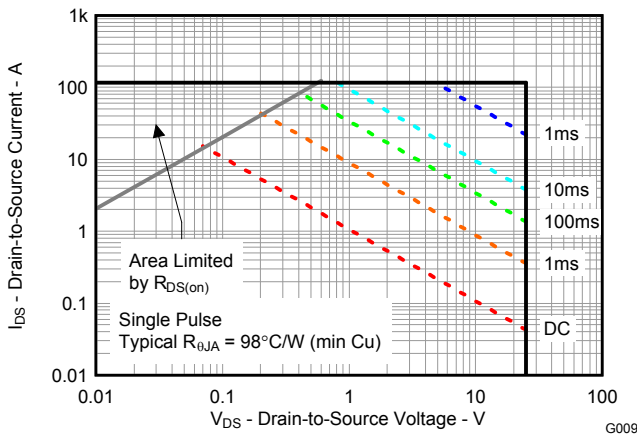


Figure 10. Maximum Safe Operating Area

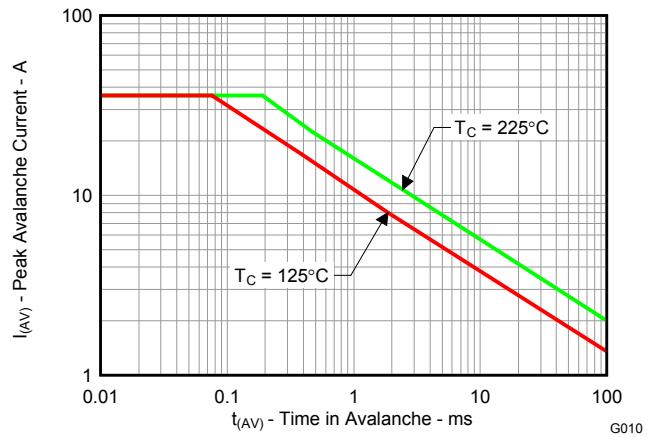


Figure 11. Single Pulse Unclamped Inductive Switching

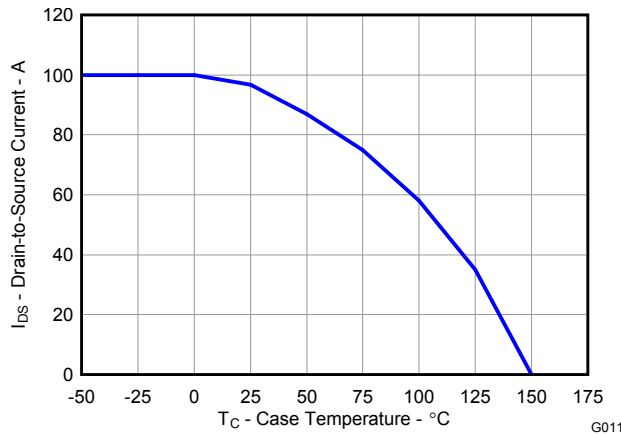
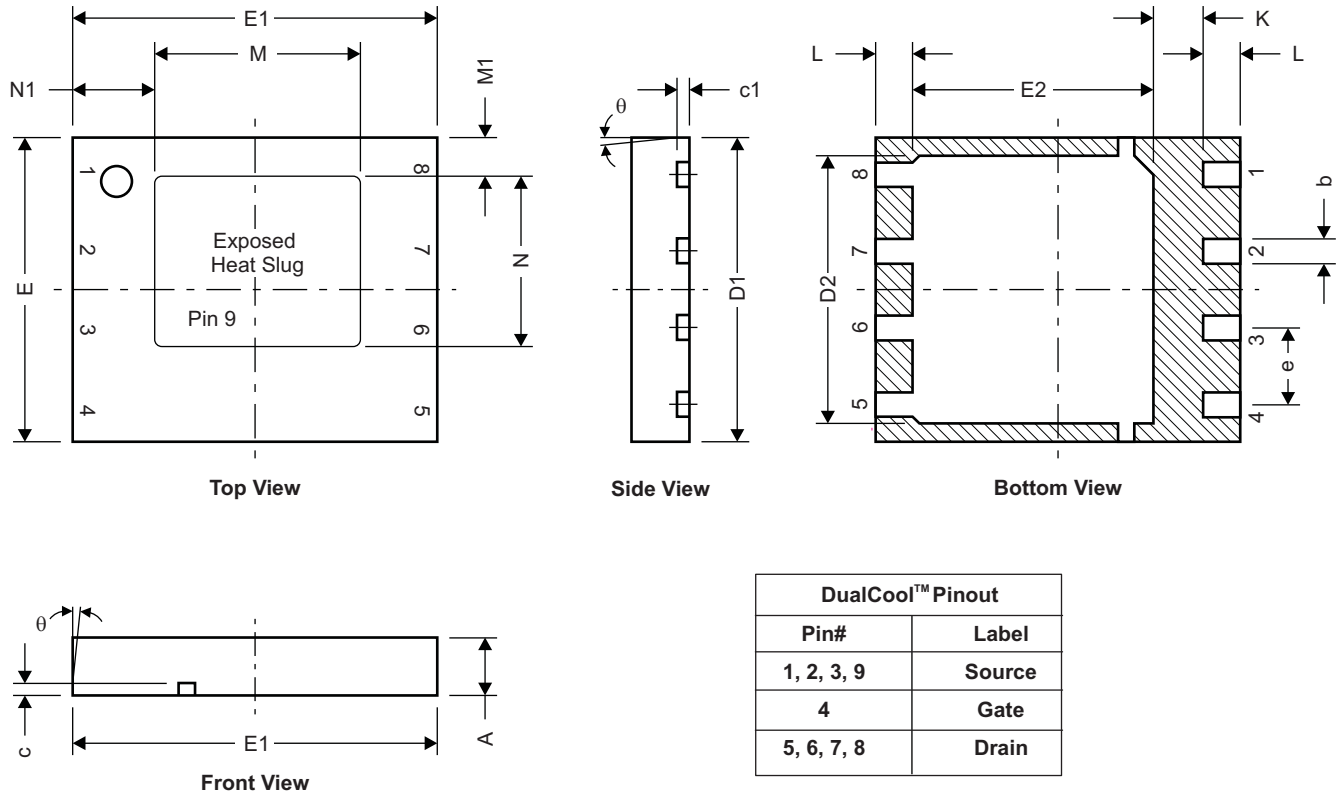


Figure 12. Maximum Drain Current vs. Temperature

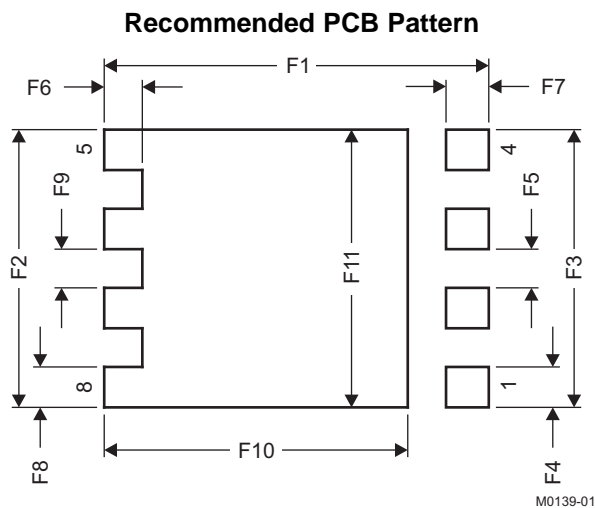
**MECHANICAL DATA**

**Q5C Package Dimensions**



M0162-01

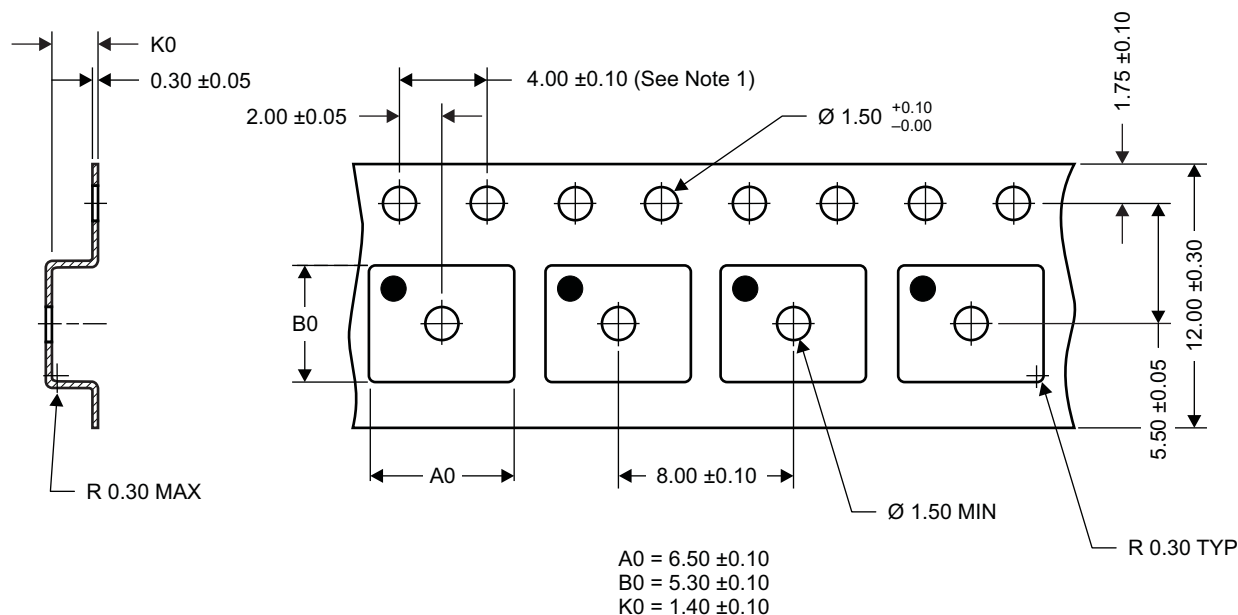
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.950	1.050	0.037	0.039
b	0.360	0.460	0.014	0.018
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
D1	4.900	5.100	0.193	0.201
D2	4.320	4.520	0.170	0.178
E	4.900	5.100	0.193	0.201
E1	5.900	6.100	0.232	0.240
E2	3.920	4.12	0.154	0.162
e	1.27 TYP		0.050	
L	0.510	0.710	0.020	0.028
θ	–	–	–	–
K	0.760	–	0.030	–
M	3.260	3.460	0.128	0.136
M1	0.520	0.720	0.020	0.028
N	2.720	2.920	0.107	0.115
N1	1.227	1.427	0.048	0.056



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.46	4.56	0.176	0.18
F3	4.46	4.56	0.176	0.18
F4	0.65	0.7	0.026	0.028
F5	0.62	0.67	0.024	0.026
F6	0.63	0.68	0.025	0.027
F7	0.7	0.8	0.028	0.031
F8	0.65	0.7	0.026	0.028
F9	0.62	0.67	0.024	0.026
F10	4.9	5	0.193	0.197
F11	4.46	4.56	0.176	0.18

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

### Q5C Tape and Reel Information



### Notes:

- 10-sprocket hole-pitch cumulative tolerance  $\pm 0.2$
- Camber not to exceed 1mm in 100mm, noncumulative over 250mm
- Material: black static-dissipative polystyrene
- All dimensions are in mm, unless otherwise specified.
- A0 and B0 measured on a plane 0.3mm above the bottom of the pocket
- MSL1 260°C (IR and convection) PbF reflow compatible

## REVISION HISTORY

### Changes from Original (December 2009) to Revision A

Page

- 
- Changed the labels on the Bottom View pinout image ..... 1
  - Changed the Mechanical Data dimensions table. Added dimensions for M, M1, N and N1 ..... 6
- 

### Changes from Revision A (April 2010) to Revision B

Page

- 
- Changed  $R_{DS(on)} - V_{GS} = 3V$  in the Electrical Characteristics table From: 7 To: 7.2 in the max column ..... 2
  - Deleted the Package Marking Information section ..... 7
-



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD16322Q5C	ACTIVE	VSON-CLIP	DQU	8	2500	Pb-Free (RoHS Exempt)	CU SN	Level-1-260C-UNLIM	-55 to 150	CSD16322C	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
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Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

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Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
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